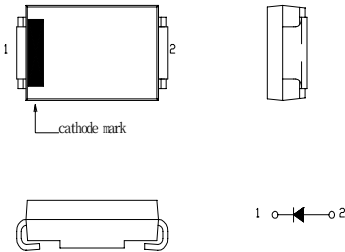


DIODE Type : NSD03A10

■OUTLINE DRAWING

構造
 : 表面実装、拡散型、整流用シリコンダイオード
 Construction: Diffusion Type Rectifier Diode
 用途
 : 一般整流用
 Application: For General Use



■最大定格 / Maximum Ratings
 Approx Net weight:0.16g

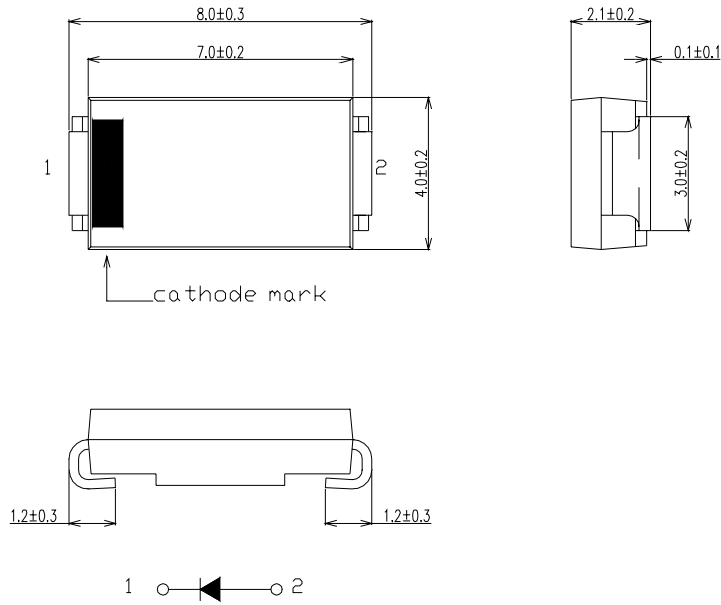
Rating	Symbol	NSD03A10			Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V _{RRM}	100			V
平均整流電流 Average Rectified Output Current	I ₀	1.57	Ta=25℃ *1	50Hz, 正弦半波通電 Half Sine Wave 抵抗負荷 Resistive Load	A
		3.0	Tl=108℃ *2		
実効順電流 RMS Forward Current	I _{F(RMS)}	4.71			A
サージ順電流 Surge Forward Current	I _{FSM}	80	50 Hz 正弦半波, 1サイクル, 非くり返し Half Sine Wave, 1cycle, Non-repetitive		A
動作接合温度範囲 Operating JunctionTemperature Range	Tjw	- 40 ～ + 150			℃
保存温度範囲 Storage Temperature Range	Tstg	- 40 ～ + 150			℃

■電氣的・熱的特性 / Electrical/Thermal Characteristics

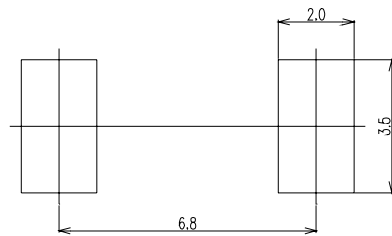
Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j = 25^{\circ}\text{C}$, $V_{RM} = V_{RRM}$	-	-	50	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j = 25^{\circ}\text{C}$, $I_{FM} = 3.0\text{A}$	-	-	1.0	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient *1	-	-	89	$^{\circ}\text{C/W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	-	-	13	

*1:Alumina Substrate mounted (Soldering Land =2×3.5mm,Both Sides)
 *2: T_l :Lead Temperature

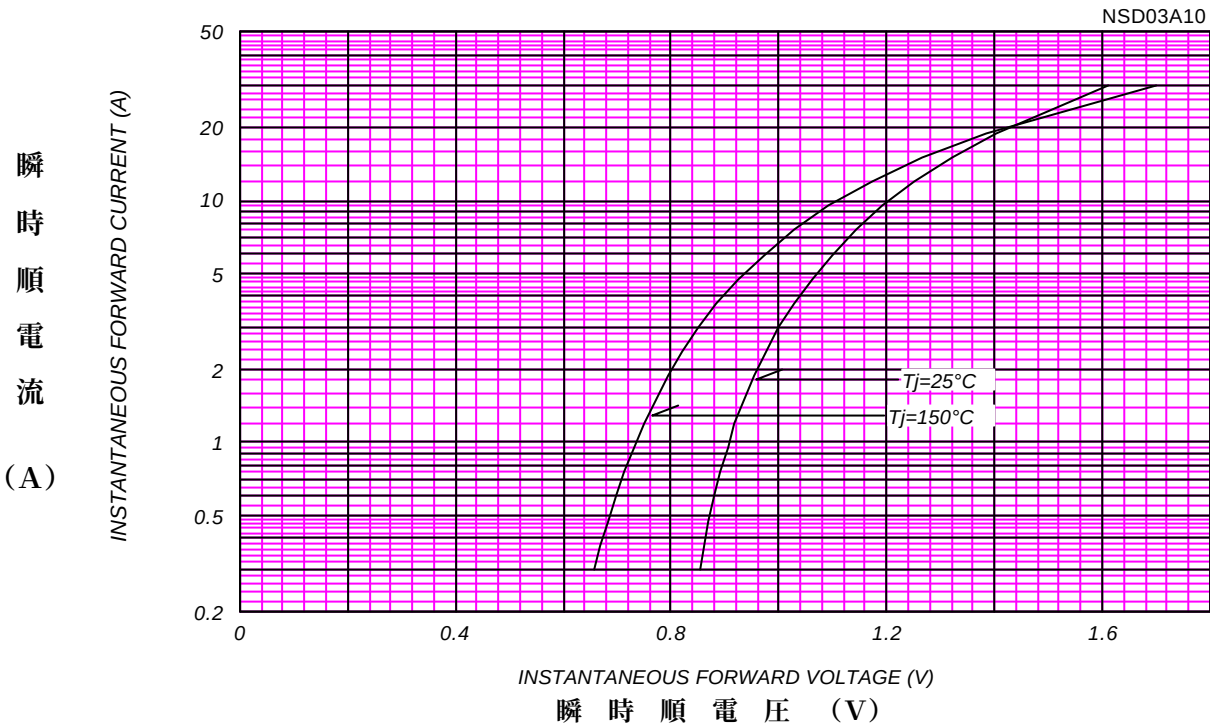
NSD03A10外形図 (mm)



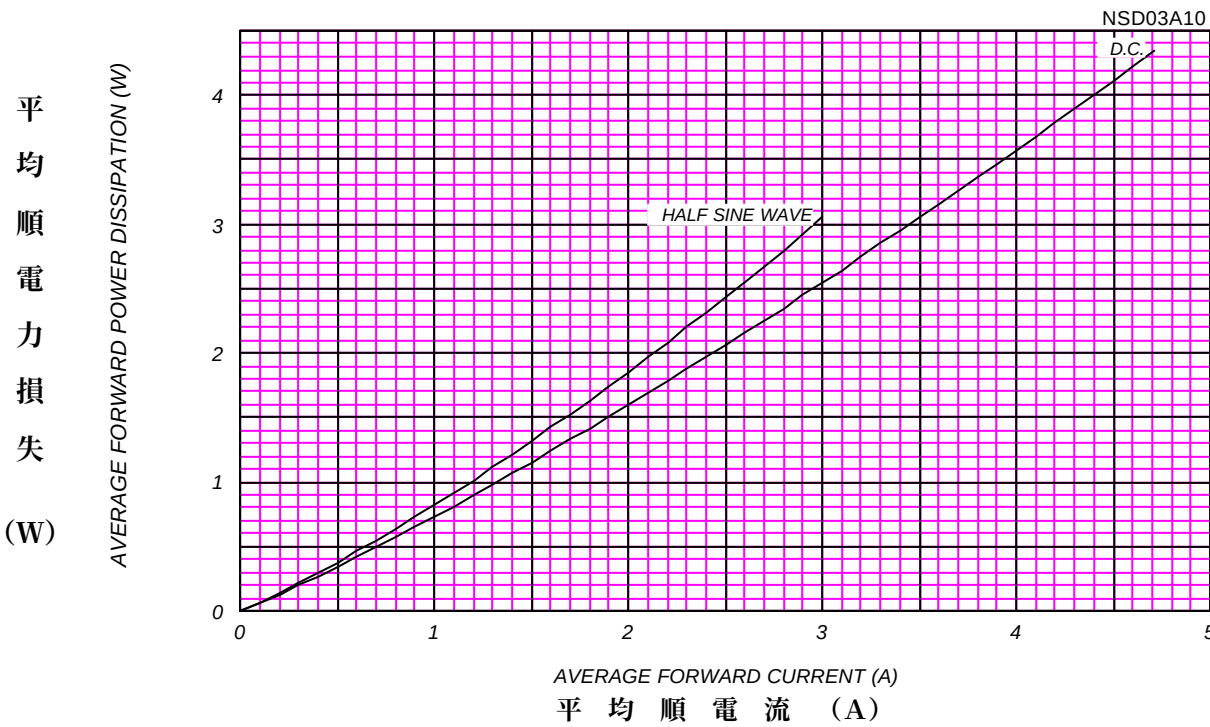
SOLDERING PAD



順電壓特性
FORWARD CURRENT VS. VOLTAGE



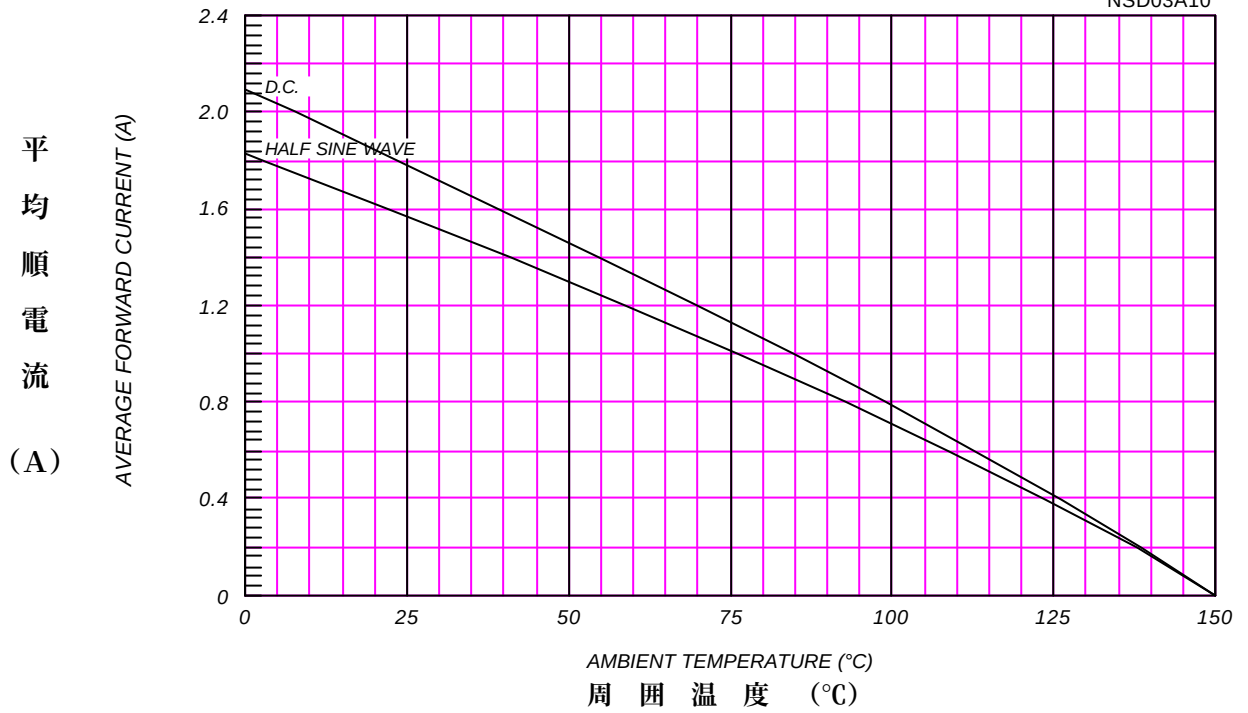
平均順電力損失特性
AVERAGE FORWARD POWER DISSIPATION



平均順電流－周圍溫度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Alumina Substrate Mounted(Soldering Land=2*3.5mm)

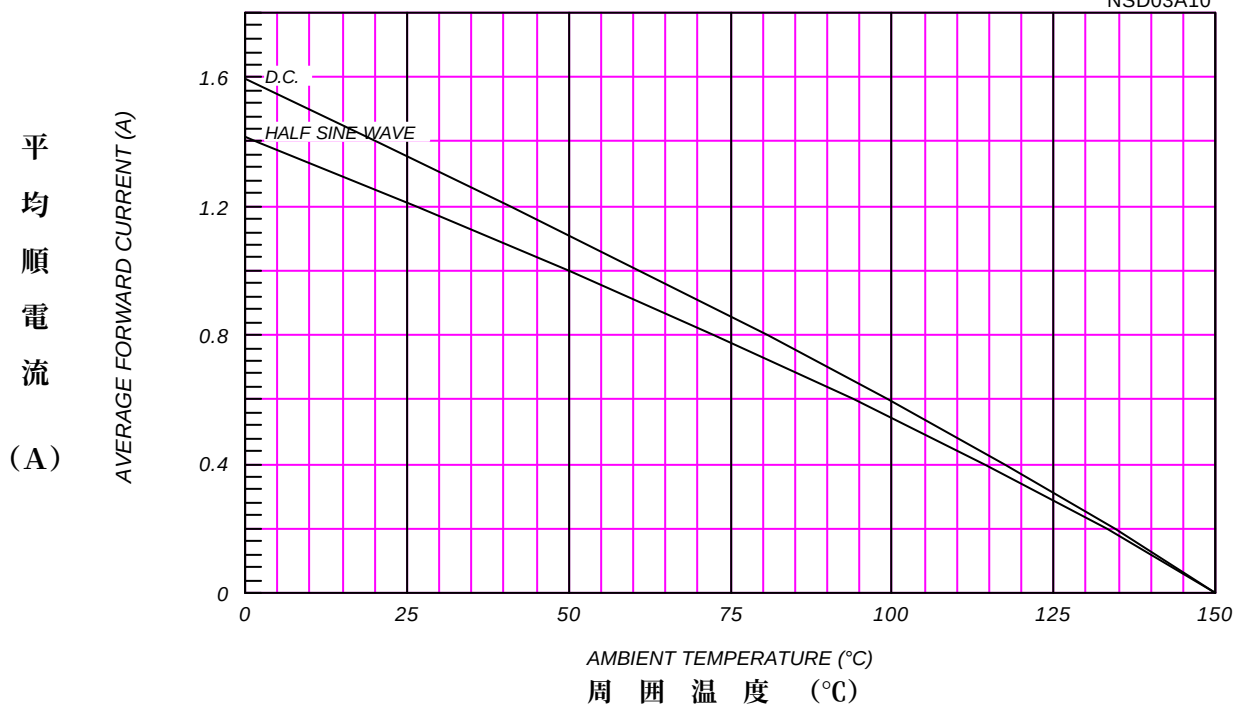
NSD03A10



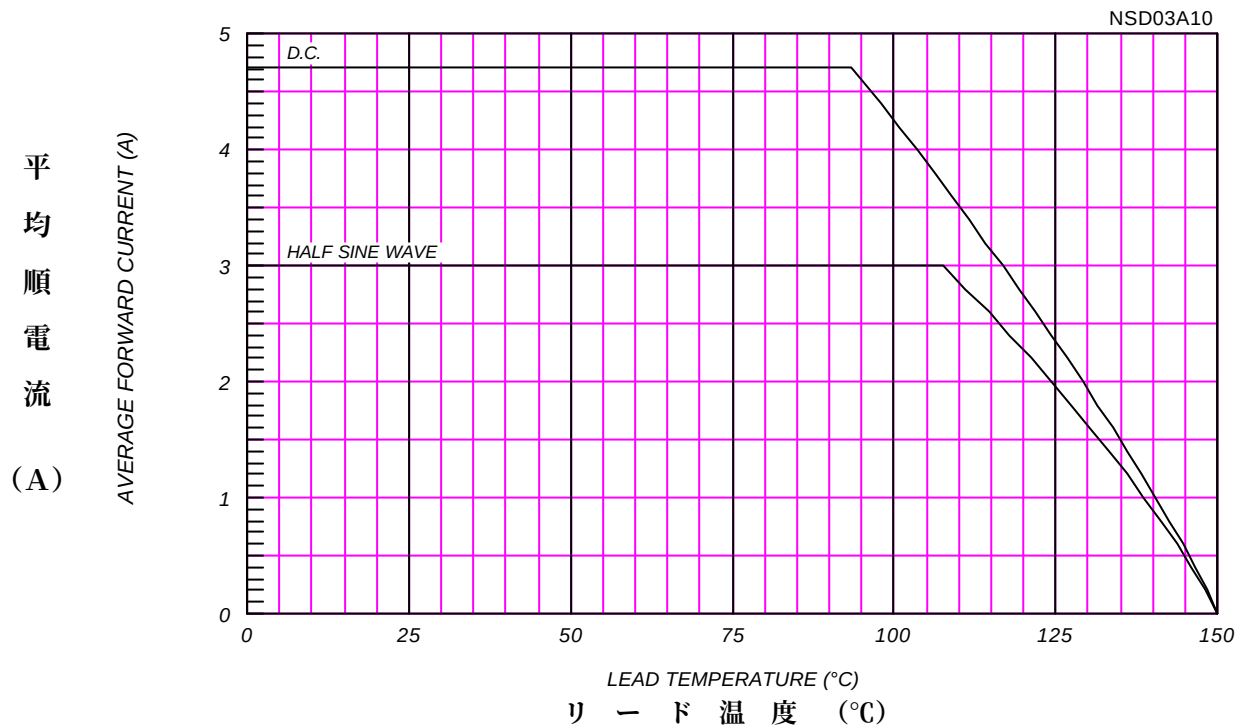
平均順電流－周圍溫度定格
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Glass-Epoxy Substrate Mounted(Soldering Land=2*3.5mm)

NSD03A10



平均順電流－リード温度定格 AVERAGE FORWARD CURRENT VS. LEAD TEMPERATURE



サージ順電流定格 SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

